



RoHS Compliant

Applications

All high density boards.

Features

- · Surface Mountable
- Solid State
- · Faster Time to Trip
- Operation Current: 0.3A to 7A
 Maximum Voltage: 6V to 60V DC
 -40°C to +85°C Temperature Range
- · Halogen Free

Electrical Characteristics

Part Number	Hold Current	Trip Current	Rated Voltage	Max. Current	Typical Power	Max. Time to Trip		Resistance	
Part Number	Iн (A)	Iτ (A)	V _{MAX} (V DC)	Імах. (А)	Pd (W)	Current (A)	Time (Sec)	R _{MIN} . (Ω)	R1 _{MAX} . (Ω)
MC011386	0.75	1.5	60	100	1.5	8	0.3	0.18	1
MC011387	1.1	2.2	60	100	1.5	8	0.5	0.09	0.41
MC011388	2	4	24	100	1.5	8	5	0.035	0.12
MC011389	2.6	5.2	6	100	1.5	8	20	0.02	0.075
MC011390	2.6	5.2	24	100	1.5	8	20	0.02	0.075
MC011391	3	5.2	6	100	1.5	8	25	0.01	0.048
MC011392	3	5.2	15	100	1.5	8	20	0.01	0.048
MC011393	3	5.2	24	100	1.5	8	20	0.01	0.048
MC011394	3.3	5.5	24	100	1.5	8	20	0.01	0.048
MC011395	4	8	16	100	1.5	20	4	0.01	0.04
MC011396	5	10	16	100	1.5	20	5	0.005	0.025

 I_{H} = Hold current-maximum current at which the device will not trip at 23°C still air.

It = Trip current-minimum current at which the device will always trip at 23°C still air.

VMAX = Maximum voltage device can withstand without damage at it rated current.(IMAX.)

IMAX = Maximum fault current device can withstand without damage at rated voltage. (VMAX.)

Pd = Typical power dissipated-type amount of power dissipated by the device when in the tripped state in 23°C still air environment.

RMIN = Minimum device resistance at 23°C prior to tripping.

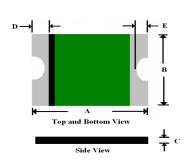
R1MAX = Maximum device resistance at 23°C measured 1 hour after tripping or reflow soldering of 260°C for 20 seconds.

Termination pad materials: Pure Tin



multicomp PRO

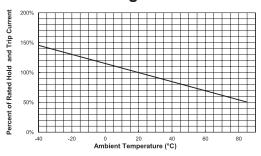
Dimensions



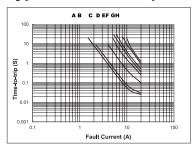
Part Number	Α		В		С		D		E	
Part Number	Min.	Max.								
MC011386	6.73	7.98	4.8	5.44	0.6	1.15	0.5	1.2	0.5	0.9
MC011387	6.73	7.98	4.8	5.44	0.4	1.7	0.5	1.2	0.5	0.9
MC011388	6.73	7.98	4.8	5.44	0.2	0.8	0.5	1.2	0.5	0.9
MC011389	6.73	7.98	4.8	5.44	0.3	0.9	0.5	1.2	0.5	0.9
MC011390	6.73	7.98	4.8	5.44	0.65	1.15	0.5	1.2	0.5	0.9
MC011391	6.73	7.98	4.8	5.44	0.4	0.9	0.5	1.2	0.5	0.9
MC011392	6.73	7.98	4.8	5.44	0.4	1.15	0.5	1.2	0.5	0.9
MC011393	6.73	7.98	4.8	5.44	0.65	1.15	0.5	1.2	0.5	0.9
MC011394	6.73	7.98	4.8	5.44	0.65	1.15	0.5	1.2	0.5	0.9
MC011395	6.73	7.98	4.8	5.44	0.4	1.5	0.5	1.2	0.5	0.9
MC011396	6.73	7.98	4.8	5.44	0.4	1.5	0.5	1.2	0.5	0.9

Dimensions: Millimetres

Thermal Derating Curve



Typical Time-To-Trip at 23°C



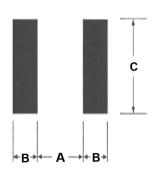
A = MC011386 B = MC011387 C = MC011388 D = MC011389 D = MC011390 E = MC011391 E = MC011393 F = MC011394 G = MC011395 H = MC011396

Material Specifications

- · Terminal Pad Material: Pure Tin
- Soldering Characteristics: Meets EIA specifications RS 186-9E, ANSI/J-std-002 Category 3

Pad Layouts - Solder Reflow and Rework Recommendations

The dimension in the table below provide the recommended pad layout.



Pad Dimensions

A	B	C		
Nominal	Nominal	Nominal		
5.1mm	2.3mm	5.6mm		





Profile Feature	Pb-Free Assembly			
Average Ramp-Up Rate (Tsmax to Tp)	3°C / second max.			
Preheat: Temperature Min (Tsmin) Temperature Max (Tsmax) Time (tsmin to tsmax)	150°C 200°C 60 - 180 seconds			
Time Maintained Above: Temperature T(L) Time t(L)	217°C 60 - 150 seconds			
Peak/Classification Temperature (Tp):	260°C			
Time within 5°C of Actual Peak: Temperature (tp)	20 - 40 seconds			
Ramp-Down Rate:	6°C / second max.			
Time 25°C to Peak Temperature:	8 minutes max.			

Note: 1. All temperature refers to the package; measured on the package body surface.

Solder Reflow:

Due to "Lead Free" nature, Temperature and Dwelling time for the soldering zone is higher than those for Regular. This may cause damage to other components.

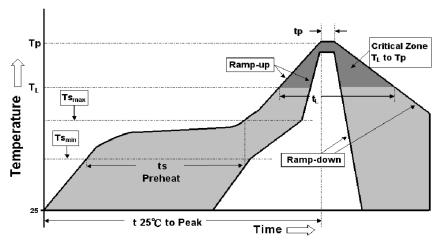
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- 1. Recommended max past thickness > 0.25mm.
- 2. Devices can be cleaned using standard methods and aqueous solvent.
- 3. Rework use standard industry practices.
- 4. Storage Environment: < 30°C / 60%RH

Caution

- 1. If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.
- 2. Devices are not designed to be wave soldered to the bottom side of the board.

Reflow Profile







Part Number Table

Description	Part Number		
PTC Resettable Fuse, 0.75A, 60V DC, 2920	MC011386		
PTC Resettable Fuse, 1.1A, 60V DC, 2920	MC011387		
PTC Resettable Fuse, 2A, 24V DC, 2920	MC011388		
PTC Resettable Fuse, 2.6A, 6V DC, 2920	MC011389		
PTC Resettable Fuse, 2.6A, 24V DC, 2920	MC011390		
PTC Resettable Fuse, 3A, 6V DC, 2920	MC011391		
PTC Resettable Fuse, 3A, 15V DC, 2920	MC011392		
PTC Resettable Fuse, 3A, 24V DC, 2920	MC011393		
PTC Resettable Fuse, 3.3A, 24V DC, 2920	MC011394		
PTC Resettable Fuse, 4A, 16V DC, 2920	MC011395		
PTC Resettable Fuse, 5A, 16V DC, 2920	MC011396		

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